



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2019-12-10
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Floriana SAN BIAGIO	Representative Title	AMS MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	IDK7*0074AE6	A	64BA-BO2A	2019-12-10
	Amount	UoM	Unit type	ST ECOPACK Grade
	130	mg	Each	ECOPACK® 3
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	0	



Package Designator	Size	Nbr of instances	Shape	
DSO	8.6 x 3.9	14	gull wing	
Comment	K7 SO 14 .15 TO JEDEC MS-012; MDF is valid for TL074IYDT			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 13th September 2019			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.17	Leadframe plating	1285

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014				
Query				Response
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products				FALSE
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products				FALSE
Hasardous substance				
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE
O	O	O	O	O

QueryList : REACH-16th July 2019				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update				
Query				Response
The Product does contain at least one of the substances listed in Chemical Control Act				NO
Substance	Homogeneous Material impacted	Content in Homogeneous Material (mg)	Concentration in the material(%)	Application Purpose

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	IDK7*0074AE6			4999999.0	1000009.0	
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	3.119	mg	supplier	die	Silicon(Si)	7440-21-3		3.065	mg	982687	23577
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.025	mg	8015	192
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.013	mg	4168	100
				supplier	passivation	Silicon oxide	7631-86-9		0.016	mg	5130	123
				supplier	alloy & coating	Copper(Cu)	7440-50-8		33.885	mg	969417	260654
Leadframe	M-004 Copper and its alloys	34.954	mg	supplier	alloy & coating	Nickel(Ni)	7440-02-0		0.167	mg	4778	1285
				supplier	alloy & coating	Iron(Fe)	7439-89-6		0.797	mg	22801	6131
				supplier	alloy & coating	Iron Phosphide(FeP)	26508-33-8		0.048	mg	1373	369
				supplier	alloy & coating	Zinc(Zn)	7440-66-6		0.042	mg	1202	323
				supplier	alloy & coating	Silver (Ag)	7440-22-4		0.003	mg	86	23
				supplier	alloy & coating	Palladium(Pd)	7440-05-3		0.005	mg	143	38
				supplier	alloy & coating	Gold(Au)	7440-57-5		0.007	mg	200	54
Die attach	M-015 Other organic materials	0.656	mg	supplier	glue	Silver(Ag)	7440-22-4		0.575	mg	876524	4423
				supplier	glue	Isobornyl methacrylate	7534-94-3		0.033	mg	50305	254
				supplier	glue	Isobornyl acrylate	5888-33-5		0.033	mg	50305	254
				supplier	glue	Methyl acrylate polymer	87320-05-6		0.013	mg	19817	100
				supplier	glue	Epoxycyclohexylethyltrimethoxysilane	3388-04-3		0.001	mg	1524	8
				supplier	glue	Tert-Butyl peroxy(2-ethyl)-hexanoate	3006-82-4		0.001	mg	1524	8
Bonding wires	M-004 Copper and its alloys	0.089	mg	supplier	wire	Copper(Cu)	7440-50-8		0.089	mg	1000000	685
Encapsulation	M-015 Other organic materials	91.183	mg	supplier	mold compound	Silica vitreous	60676-86-0		78.964	mg	865995	607415
				supplier	mold compound	Epoxy type resin	proprietary		6.839	mg	75003	52608
				supplier	mold compound	Phenol type resin	proprietary		4.559	mg	49998	35069
				supplier	mold compound	Carbon black	1333-86-4		0.456	mg	5001	3508
				supplier	mold compound	Bismuth compound	7440-69-9		0.365	mg	4003	2808